Product Change Notification: MFOL-04DKIC547

Date:

05-Mar-2025

Product Category:

Memory

Notification Subject:

CCB 7372 Final Notice: Qualification of CuPdAu as a new wire material, AMK-06 as a new die attach material, and G631BQF as a new mold compound for AT24C128C-MAHM-T and AT24C128C-MAHM-E catalog part numbers (CPN) available in 8L UDFN (2x3x0.6mm) package assembled at ATP7 assembly site.

Affected CPNs:

MFOL-04DKIC547_Affected_CPN_03052025.pdf
MFOL-04DKIC547_Affected_CPN_03052025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CuPdAu as a new wire material, AMK-06 as a new die attach material, and G631BQF as a new mold compound for AT24C128C-MAHM-T and AT24C128C-MAHM-E catalog part numbers (CPN) available in 8L UDFN (2x3x0.6mm) package assembled at ATP7 assembly site.

Pre and Post Summary Changes:

	Pre Change			**Post Change**	
Assembly Site	ASE Inc. (ASE)	Amkor Technology Philippines	Microchip Technology Thailand	Amkor Technology Philippines	Microchip Technology Thailand

		(P3/P4), INC. (ATP7)	(Branch) (MMT)	(P3/P4), INC. (ATP7)	(Branch) (MMT)
Wire Material	PdCu	PdCu	CuPdAu	**CuPdAu**	CuPdAu
Die Attach Material	EN-4900G	CRM-1085 A	8600	**AMK-06**	8600
Molding Compound Material	G631H	G700Y	G700LTD	**G631BQF**	G700LTD
Lead-Frame Material	C7025	C7025	EFTEC-64T	C7025	EFTEC-64T

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CuPdAu as a new wire material, AMK-06 as an new die attach material, and G631BQF as a new mold compound.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 March 2025 (date code: 2513)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2025					**March 2025**				
Work Week	05	06	07	08	09	10	11	12	13	14
Qual Report Availability			X							
Final PCN Issue Date			X							

Estimated Implementation Date									X	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 14, 2025: Issued final notification.
February 21, 2025: Re-issued final notification to remove the pre and post change comparison for the leadframe drawing as there is no change. Revised the "Notification subject", "Description of change", "Qual report title and purpose" to remove the MMT site as there is only a change for ATP7.
March 05, 2025: Re-issued final notification to revised the Qual Report to reflect ATP7 only and remove the LF design in pre and post change as there is no change.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-04DKIC547__QUAL_REPORT.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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